

Specifications

Insulation Resistance



SMD Comm X7R FO, Ceramic, 0.33 uF, 20%, 100 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X7R FO
Style	SMD Chip
Description	SMD, MLCC, Open Mode, Temperature Stable
Features	Open Mode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	55 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	1.6mm +/-0.25mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

0.33 uF
1 kHz 1.0Vrms
20%
100 VDC
250 VDC
-55/+125°C
X7R
15%, 1kHz 1.0Vrms
2.5% 1 kHz 1.0 Vrms
3% Loss/Decade Hour: Referee Time is 1000 Hours

3.0303 GOhms

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	8000

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